

NOTES

- 1 FOR INDIVIDUAL DECK ASSEMBLY DETAILS, REFER TO MO-199.
- 2 DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 3 ALL DIMENSIONS IN MILLIMETERS.
- 4 N IS THE MAXIMUM NUMBER OF LEADS.

5 TO BE DETERMINED AT SEATING PLANE C.

6 DIMENSION b4 DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE SHOULDER WIDTH TO EXCEED b4 MAXIMUM BY MORE THAN X mm. THE DAMBAR INTRUSION(S) SHALL NOT REDUCE THE SHOULDER WIDTH TO LESS THAN 0.03 mm BELOW B4 MINIMUM.

e	X
1.27	0.13
0.80	0.08
0.65	0.08

7 THE LEAD 1 IDENTIFIER AND LEAD NUMBERING CONVENTION SHALL CONFORM TO JESD 95 SPP-012. DETAILS OF LEAD 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE LEAD 1 IDENTIFIER MAY BE EITHER A MOLDED OR A MARKED FEATURE.

8 FOR TWO HIGH VARIATIONS (Ax), LEADS OF UPPER DEVICE MUST BE CENTRAL TO LEADS OF BOTTOM DEVICE WITHIN ± 0.13 mm. FOR FOUR HIGH VARIATIONS (Bx), ADJOINING DEVICE LEADS MUST BE CENTRAL WITHIN ± 0.13 mm, WITH THE TOTAL VARIATION WITHIN THE STACKED ASSEMBLY TO BE ± 0.20 mm

9 DATUM A AND B ARE ESTABLISHED ON THE BOTTOM DECK OF THE 2 OR 4 HIGH ASSEMBLY.

10 DIMENSION E IS MEASURED AT THE WIDEST POINT OF THE STACK ASSEMBLY AND INCLUDES ANY SOLDER FILLET PROTRUSION.

JEDEC
SOLID STATE
PRODUCT OUTLINE

THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE SMALL OUTLINE
J-LEAD PACKAGE ASSEMBLY
2 HIGH/4 HIGH STACK

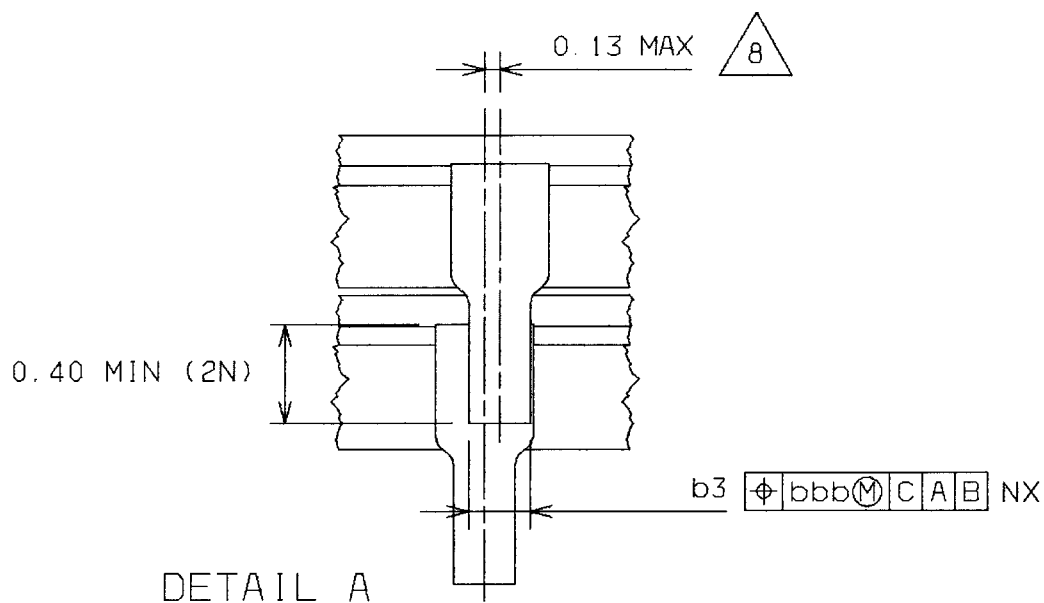
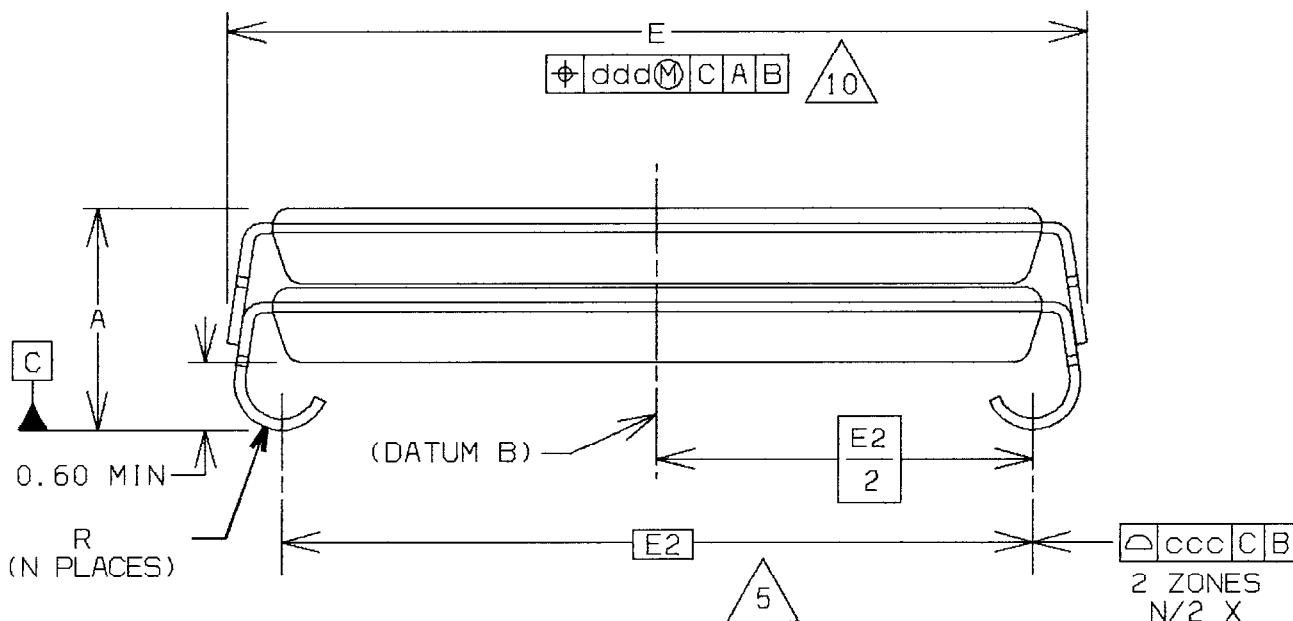
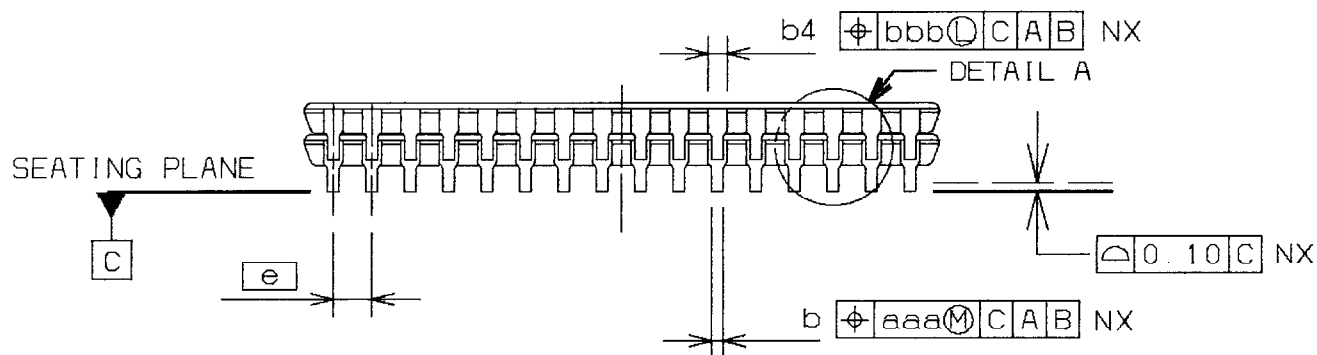
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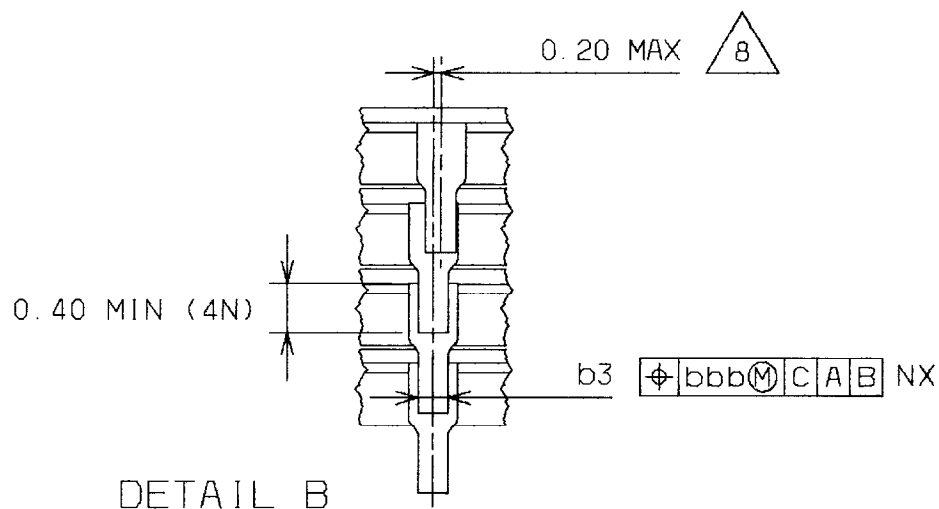
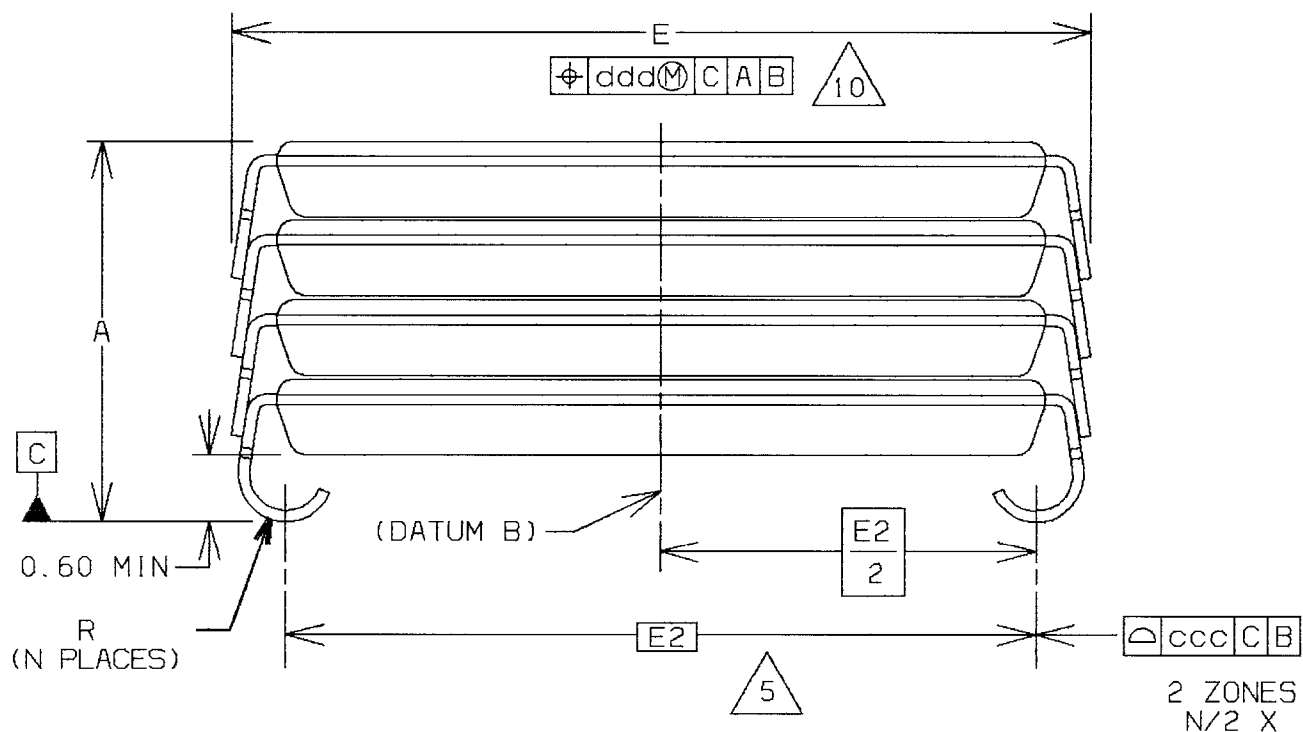
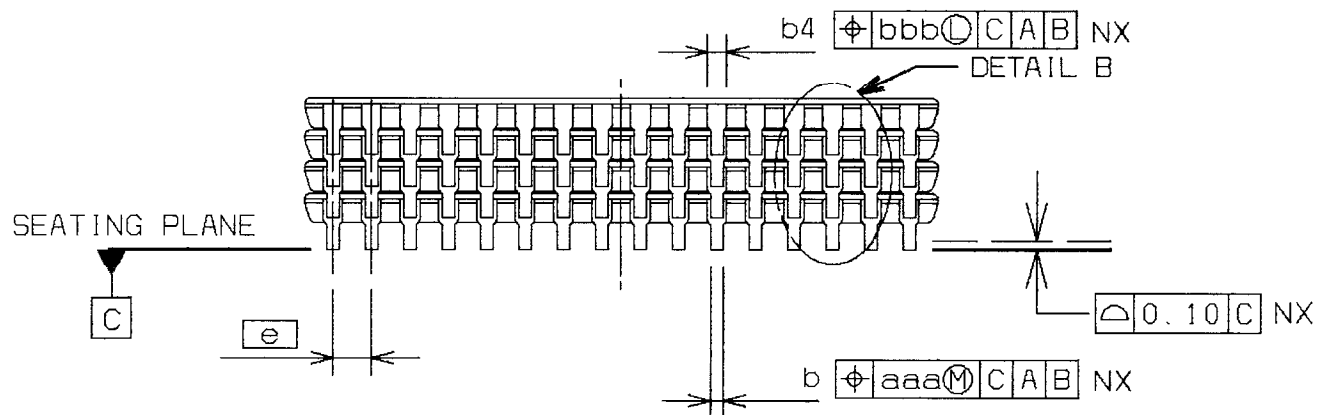
ISSUE
B

DATE
6/99

MO-200

1
OF 5





SYMBOL	COMMON DIMENSIONS			NOTE
	DIMENSIONS IN MILLIMETERS			
	MIN	NOM	MAX	
E1	10.15 BASIC			5
E2	9.90 BASIC			
R	0.55	0.65	0.75	

COMMON TOLERANCES				
ccc	0.40			5
ddd	0.15			

NOTE	2, 3			
REF.	11-481			
ISSUE	A			

SYMBOL	VARIATIONS												NOTE
	AA			AB			BA			BB			
	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
A	--	--	3.20	--	--	3.20	--	--	5.50	--	--	5.50	6
b	0.36	--	0.52	0.26	--	0.40	0.36	--	0.52	0.26	--	0.40	
b3	0.36	0.40	0.44	0.26	0.30	0.34	0.36	0.40	0.44	0.26	0.30	0.34	
b4	0.62	0.66	0.79	0.46	0.50	0.63	0.62	0.66	0.79	0.46	0.50	0.63	
D	20.95 BASIC			18.40 BASIC			20.95 BASIC			18.40 BASIC			
E	11.15	11.40	11.65	11.15	11.40	11.65	11.15	11.40	11.65	11.15	11.40	11.65	
e	1.27 BASIC			0.80 BASIC			1.27 BASIC			0.80 BASIC			4
N	32			44			32			44			
aaa	0.20			0.20			0.20			0.20			
bbb	0.20			0.20			0.20			0.20			
NOTE	1, 2, 3			1, 2, 3			1, 2, 3			1, 2, 3			
REF.	11-481			11-481			11-481			11-481			
ISSUE	A			A			A			A			
JEDEC SOLID STATE PRODUCT OUTLINE			SMALL OUTLINE J-LEAD PACKAGE ASSEMBLY 2 HIGH/4 HIGH STACK					ISSUE B	DATE 6/99	MO-200		4 OF 5	

